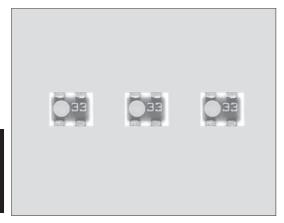
CNNI薄膜网络电阻器(贴片) Thin Film Chip Networks

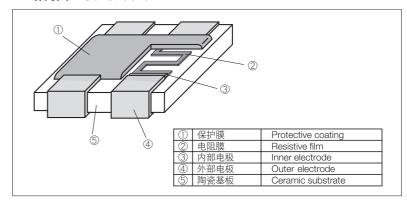


外观颜色:绿色(CNN) Coating color: Green (CNN)

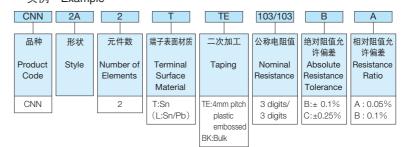
■ 特点 Features

- 具有金属薄膜的网络电阻器 (贴片) 电阻器。
- ●相对于T.C.R.,具有更优异的相对精度。
- 高精度OP Amp用配对电阻。
- ●适用于定制组合1kΩ到100kΩ之间任意的电阻值。
- ●适用于回流焊接。
- ●端子无铅品,符合欧盟RoHS。
- Metal film chip network resistors.
- Excellent in relative T.C.R. and relative accuracy.
- Pair resistors for high precision OP-Amplifiers.
- \bullet As custom products, any pairs between $1k\,\Omega$ and $100k\,\Omega$ are available on request.
- Suitableforreflow soldering.
- Products with lead free termination meet EU-RoHS requirements.

■ 结构图 Construction



■ 品名构成 Type Designation 实例 Example



端子表面材质,以无铅品为准。

欲知关于此产品含有的环境负荷物质详情(除EU-RoHS以外),请与我们联系。

编带细节请参考卷末附录C。

The terminal surface material lead free is standard.

Contact us when you have control request for environmental hazardous material other than the substance specified by EU-RoHS.

For further information on taping, please refer to APPENDIX C on the back pages.

■ 参考标准 Reference Standards

IEC 60115-1 JIS C 5201-1

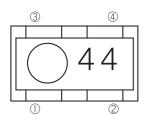
■ 额定值 Ratings

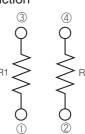
型 号	工)		阻值允许偏差 电阻温度 Resistance Tolerance T.C.R.(×1			× 10 ⁻⁶ /K)				使用温度范围	编带和包装数/卷 Taping & Q'ty /Reel (pcs)	
Type (Inch Size)	Power Rating	Resistance (Ω)	绝对 Absolute	相对 Relative	绝对 Absolute	相对	Max. Working Voltage	Max. Overload Voltage	Max. Overload Voltage	Max. Overload Voltage	TE	
CNN2A (0805×2)	0.05W/ Element	1k, 10k, 100k	B:±0.1% C:±0.25%	A:0.05% B:0.1%	±25	5	50V	100V	+70°C	-55°C∼+125°C	4,000	

额定电压是√额定功率×公称电阻值所算出的值或表中最高使用电压两者中小的值成为额定电压。

Rated voltage = $\sqrt{\text{Power Rating} \times \text{Resistance value}}$ or Max. working voltage, whichever is lower.

■ 电路构成 Circuit Construction





● 标准品 Standard

电阻值 Resistance											
R1	1kΩ	1k	Ω		1kΩ	10kΩ	10	10kΩ		100kΩ	
R2	1kΩ	10k	OkΩ		00kΩ	10kΩ	100	100kΩ		100kΩ	
First ma	3		3	3	4	4		5			
Second r	3		4	5	4	5		5			

● 定制品 Custom

可以适用于定制 $1k\Omega$ 到 $100k\Omega$ 之间任意电阻值。

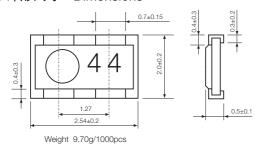
关于定制产品,请您事前咨询。

Custom products of any pairs between $1k\Omega$ and $100k\Omega$ are available on request.

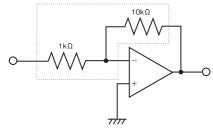
Please ask us beforehand for the custom products.



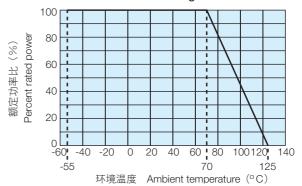
■ 外形尺寸 **Dimensions**



■ 应用范例 **Examples For Application**



■ 负荷减轻特性曲线 **Derating Curve**



在环境温度70℃以上使用时,应按照上图负荷减轻特性曲线,减小额定功率。 For resistors operated at an ambient temperature of 70°C or above, a power rating shall be derated in accordance with the above derating curve.

■ 性能 Performance

试验项目 Test Items	标准值 Performance Requirements Absolute ΔR± (%+0.05 Ω)		试验方法 Test Methods				
rest items	保证值 Limit	代表值 Typical					
电阻值 Resistance	在规定的允许偏差内 Within specified tolerance	_	25°C				
电阻温度系数 T.C.R.	在规定值以内 Within specified T.C.R.	_	+25°C/-55°C and +25°C/+125°C				
过载(短时间) Overload(Short time)	0.1	0.01	额定电压的2.5倍或者最高过载电压,择其低者施加5秒 Rated voltage×2.5 or Max. overload vol., whichever less, for 5s				
耐焊接热 Resistance to soldering heat	0.1	0.02	260°C±5°C, 10s±1s				
温度突变 Rapid change of temperature	0.25	0.01	-55°C (30min.) /+125°C (30min.) 5 cycles				
耐湿负荷 Moisture resistance	0.25	0.03	40℃±2℃, 90%~95%RH, 1000h 1.5小时ON、0.5小时OFF的周期 1.5h ON/0.5h OFF cycle				
在70℃时的耐久性 Endurance at 70℃	0.25	0.03	70℃±2℃, 1000h 1.5小时ON、0.5小时OFF的周期 1.5h ON/0.5h OFF cycle				
高温放置 High temperature exposure	0.25	0.02	CNN: 125°C, 100h				

■ 使用注意事项 Precautions for Use

- 对于产品的编带材料已经采用了防止静电的合适措施,但在实际安装时,如果遇到特别干燥的场合,或者由于长时间包装在编带内并加之振动,产品会从上层编带吸 附静电,这些情况将会导致安装失败,或者部件受到静电(人体模型100pF,1.5kΩ相当于1KV)破坏电阻发生变化等情况的危险,请务必加以注意。在PCB表面封装 时,同样请注意不要受到过度静电的影响。
- 在本产品和安装的印刷电路板上,附着了助焊剂和人的汗和唾液等离子性杂质时,耐湿性・耐腐蚀性等方面会变得不理想。产品被助焊剂中含有的氯和酸,人的汗, 唾液中含有的纳,氯等离子污染时,已证实会引起电蚀。特别是使用无助焊剂时,由于湿润性的提高,会含有大量离子性物质,所以使用RMA系的焊锡或助焊剂时, 请进行充分清洗。并且,涂上防湿涂层材料时,在产品和防湿涂层之间残留了上述杂志时,会引起进一步电蚀,因此,请在涂防湿材料前清洗。
- 此外,请注意,如果烙铁直接接触了保护涂层,保护涂层有可能发生瞬时碳化,这将降低对电腐蚀的抵抗性以及保护涂层的绝缘性。更需要注意的是,烙铁的温度很 高时,同样会影响保护涂层的性能。
- 产品存放时,请避免日光直射、高温和潮湿。日光直射会引起编带的变质,难以维持适当的编带强度,请务必加以注意。在5~35℃/35~75%RH以下的场合,购人12个月 之内,其焊接性不会降低。由于凝露、有毒气体(硫化氢、亚硫酸气体、氯化氢)和灰尘会导致焊接性降低,在保管时请加以注意。
- 耐热屏蔽胶带连接到安装的芯片电阻器,上部电极可能被剥离。据证实,由于暴露载在高温下安装附着力变得更加牢固。因此,我们建议控制使用胶带。如果耐热屏 蔽胶带不可避免被使用, 请确保胶带粘合剂不直接与产品接触。
- The properly and electrostatically measured taping materials are used for the components, but attention should be paid to the fact that there is some danger the parts absorb on the top tapes to cause a failure in the mounting and the parts are destructed by static electricity (1kV and more, Human Body Model 100pF 1.5k \Omega) to change the resistance in the conditions of an excessive dryness or after the parts are given vibration for a long time as they are packaged on the tapes. Similarly, care should be given not to apply the excessive static electricity when mounting on the boards.
- Ionic impurities such as flux etc. that are attached to these products or those mounted onto a PCB, negatively affect their moisture resistance, corrosion resistance, etc. The flux may contain ionic substances like chlorine, acid, etc. while perspiration and saliva include ionic impurities like sodium (Na⁺), chrorine (Cl⁻) etc. Therefore these kinds of ionic substances may induce electrical corrosion when they invade into the products. Either thorough washing or using RMA solder and flux are necessary since lead free solder contains ionic substances. Washing process is needed, before putting on moisture proof material in order to prevent electrical corrosion.
- Please pay attention that the top of an iron does not direct touch to the components. There is a risk that may cause a change in resistance. Take care that another risk may happen that the protecting coat is carbonized in an instant when touched directly by the top of the iron, also climatic-proof for electric corrosion or insulation of protecting coat may be dropped down. Be sure not to give high temperature on the top of the iron as it will degrade the protecting coat.
- Avoid storing components under direct sun rays, high temperature/humidity. Direct sun rays will cause quality change of taping and difficulty of keeping appropriate peeling strength. In the case of $5\sim35^{\circ}$ C/35 $\sim75\%$ RH, there is no deterioration of solderability for 12 months, but take special care for storing, because condensation, dust, and toxic gas like hydrogen sulfide, sulfurous acid gas, hydrogen chloride, etc. may drop solderability.
- The upper electrodes could be peeled off when a heat-resistant masking tape is attached to the mounted chip resistors and then detached from them. It is confirmed that the adhesiveness gets stronger due to the exposure to heat under mounting. Accordingly, we recommend the use of masking tape be refrained. If the use of heat-resistant masking tape is unavoidable, please make sure that the adhesives on the tape do not directly come in contact with the product.